

Serial No.: 10/783,823

**AMENDMENTS TO THE CLAIMS:**

The following listing of claims replaces all prior listings of claims in the present application.

**What Is Claimed Is:**

**1. (previously presented) A temperature-compensated crystal oscillator comprising:**

a substrate having a circuit pattern disposed on a surface thereof and mounting electrodes disposed on a reverse side thereof and electrically connected to said circuit pattern;

circuit components mounted on the surface of said substrate and electrically connected to said circuit pattern; and

a surface-mount crystal unit having a ~~hermetically sealed~~ crystal unit, and mounted on the surface of said substrate and electrically connected to said circuit pattern, the crystal unit being hermetically sealed in a casing independent of said substrate;

said crystal unit having a cavity defined in a mounting surface thereof, at least one of said circuit components being housed in said cavity, ~~and at least one of the remaining circuit components is being disposed outside of said cavity, and wherein the casing of the hermetically sealed crystal unit is not directly mounted on the substrate.~~

**2. (original) The temperature-compensated crystal oscillator according to claim 1, further comprising a temperature-compensating circuit, said temperature-compensating circuit comprising circuit components housed in said cavity.**

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**3. (original)** The temperature-compensated crystal oscillator according to claim 2, wherein said temperature-compensated circuit is directly connected to said crystal unit, whereby the temperature-compensated crystal oscillator serves as a temperature-compensated crystal oscillator of the direct compensation type.

**4. (original)** The temperature-compensated crystal oscillator according to claim 2, further comprising an adjusting capacitor for equalizing an oscillation frequency at a predetermined temperature to a target frequency, said adjusting capacitor being mounted on the surface of said substrate and disposed outside of said cavity.

**5. (original)** The temperature-compensated crystal oscillator according to claim 1, wherein said circuit components which are disposed in said cavity comprise chip-type circuit components each having a size of 0.6mm x 0.3mm.

**6. (original)** The temperature-compensated crystal oscillator according to claim 2, further comprising a variable capacitance diode for changing an oscillation frequency depending on a control voltage supplied from an external circuit, said variable capacitance diode being mounted on the surface of said substrate and disposed outside of said cavity.

**7. (previously presented)** The temperature-compensated crystal oscillator according to claim 2, wherein the temperature-compensating circuit is formed as a chip-type circuit component.

**8-9. (canceled)**